



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

July 29, 2009

Applicant: Chisato HOSHINO  
For: THERMAL CONDUCTIVE SILICONE COMPOSITION  
Serial No.: 10/567 587 Group: 1796  
Confirmation No.: 2543  
Filed: August 24, 2006 Examiner: Ojurongbe  
International Application No.: PCT/JP2004/014679  
International Filing Date: September 29, 2004  
Atty. Docket No.: 3400.P1429US

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Sir:

In response to the Office Action dated April 30, 2009,  
please amend the above-identified application as follows:

(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
sufficient postage as first class mail in an envelope  
addressed to: Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450, on July 29, 2009.

  
Terryence F. Chapman